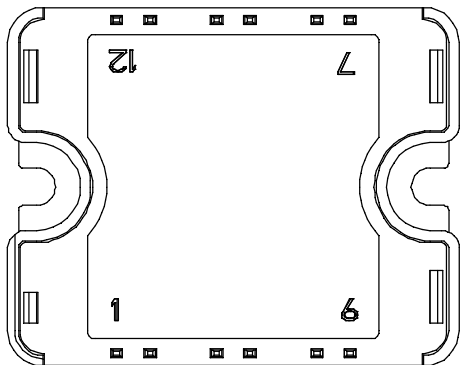
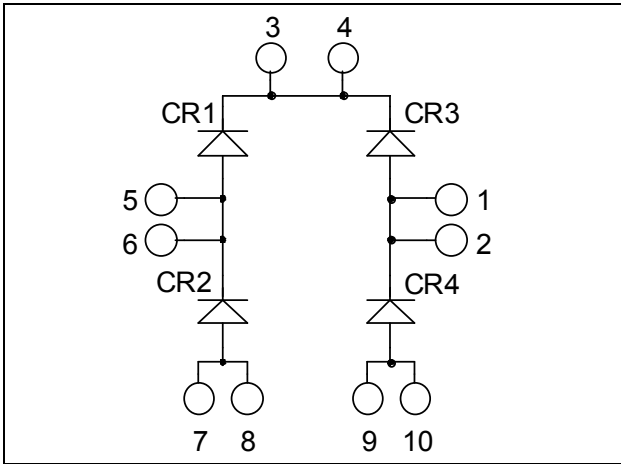


Fast Diode Full Bridge Power Module

$V_{RRM} = 600V$
 $I_C = 100A^* @ T_c = 80^\circ C$



Application

- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers

Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Solderable terminals for easy PCB mounting
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

All multiple inputs and outputs must be shorted together
 3/4 ; 5/6 ; 7/8 ; 1/2 ; 9/10

Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_R	Maximum DC reverse Voltage	600	V
V_{RRM}	Maximum Peak Repetitive Reverse Voltage		
$I_{F(AV)}$	Maximum Average Forward Current	Duty cycle = 50%	A
		$T_C = 25^\circ C$	
		$T_C = 80^\circ C$	100 *
I_{FSM}	Non-Repetitive Forward Surge Current	8.3ms	500
		$T_C = 45^\circ C$	

* Specification of diode device but output current must be limited to 75A to not exceed a delta of temperature greater than 30°C for the connectors.

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

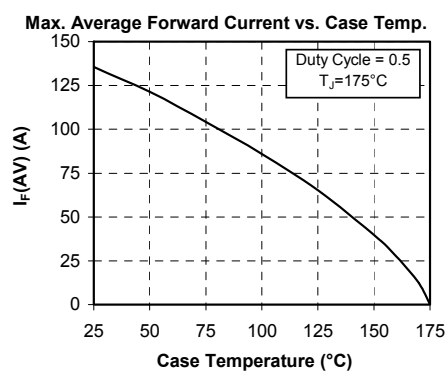
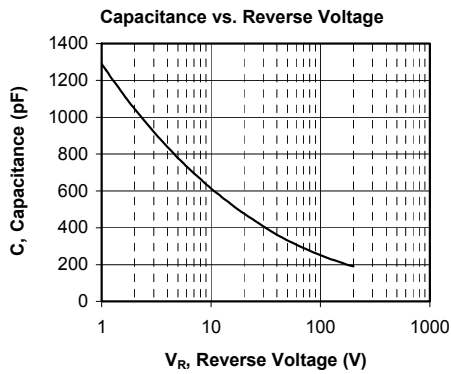
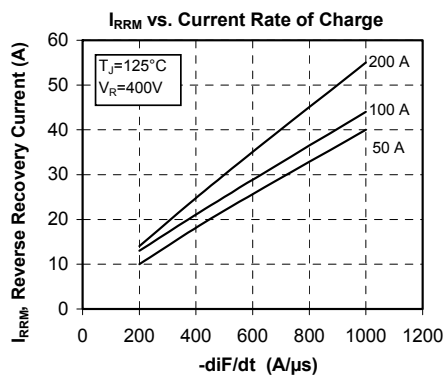
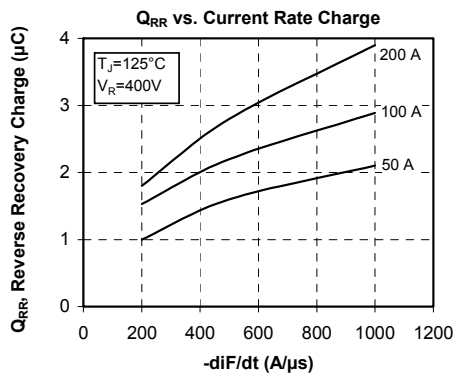
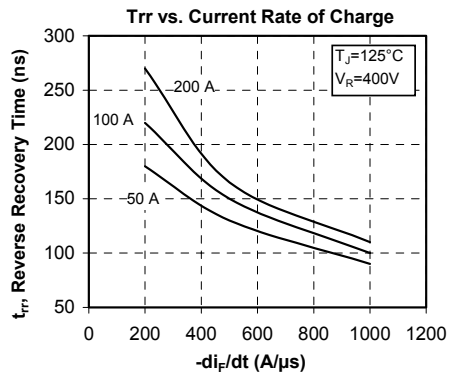
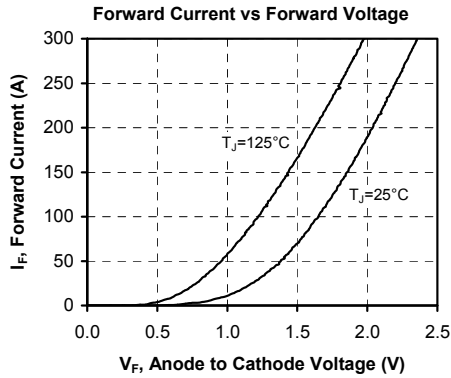
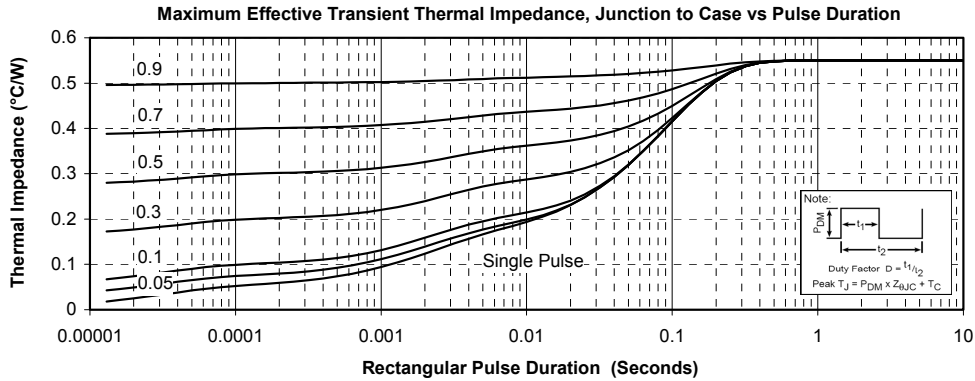
Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V_F	Diode Forward Voltage	$I_F = 100\text{A}$		1.6	2.0	V
		$I_F = 200\text{A}$		2.0		
		$I_F = 100\text{A}$	$T_j = 125^\circ\text{C}$	1.3		
I_{RM}	Maximum Reverse Leakage Current	$V_R = 600\text{V}$	$T_j = 25^\circ\text{C}$		250	μA
			$T_j = 125^\circ\text{C}$		500	
C_T	Junction Capacitance	$V_R = 200\text{V}$		190		pF

Dynamic Characteristics

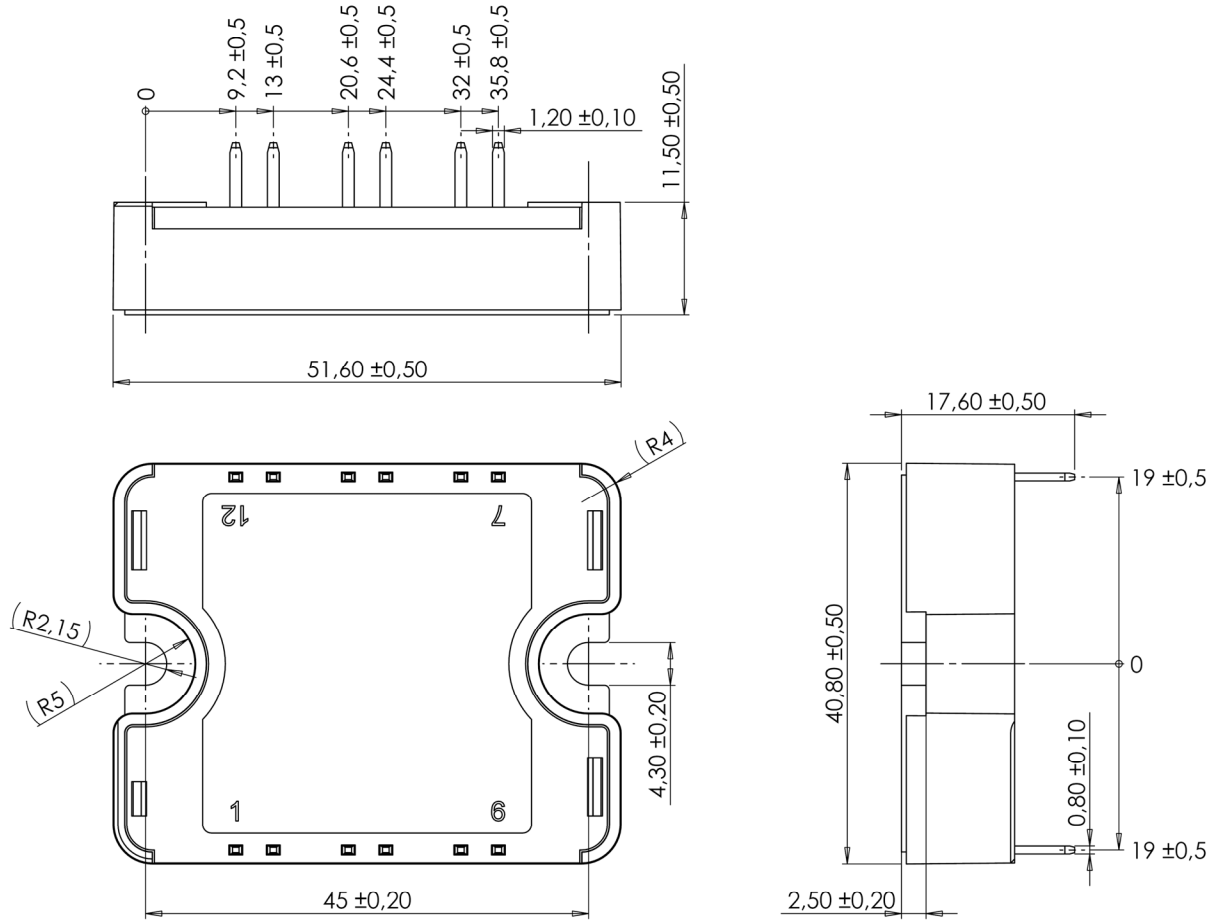
Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
t_{rr}	Reverse Recovery Time	$I_F = 100\text{A}$ $V_R = 400\text{V}$ $di/dt = 200\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$		160	ns
			$T_j = 125^\circ\text{C}$		220	
Q_{rr}	Reverse Recovery Charge	$I_F = 100\text{A}$ $V_R = 400\text{V}$ $di/dt = 200\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$		290	nC
			$T_j = 125^\circ\text{C}$		1530	
I_{RRM}	Reverse Recovery Current	$I_F = 100\text{A}$ $V_R = 400\text{V}$ $di/dt = 200\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$		5	A
			$T_j = 125^\circ\text{C}$		13	
t_{rr}	Reverse Recovery Time	$I_F = 100\text{A}$ $V_R = 400\text{V}$ $di/dt = 1000\text{A}/\mu\text{s}$	$T_j = 125^\circ\text{C}$		100	ns
Q_{rr}	Reverse Recovery Charge				2890	nC
I_{RRM}	Reverse Recovery Current				44	A

Thermal and package characteristics

Symbol	Characteristic	Min	Typ	Max	Unit	
R_{thJC}	Junction to Case Thermal Resistance			0.55	$^\circ\text{C}/\text{W}$	
V_{ISOL}	RMS Isolation Voltage, any terminal to case $t = 1\text{ min}$, 50/60Hz	4000			V	
T_j	Operating junction temperature range	-40		175	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-40		125		
T_C	Operating Case Temperature	-40		100		
Torque	Mounting torque	To heatsink	M4	2	3	N.m
Wt	Package Weight				80	g

Typical Performance Curve


SP1 Package outline (dimensions in mm)



See application note 1904 - Mounting Instructions for SP1 Power Modules on www.microsemi.com

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